



Data Sheet
Dexnyl™ 232 PI-s-Powders Nat.

Product Description

Thermosetting Polyimide (PI-s), natural granule suitable for molding and compounding

Applications

- Can be used as a compounding material to produce parts and/or coatings with enhanced thermal properties
- To produce high temperature, self-lubricant and wear resistance semi-finished and finished parts through compression molding or direct forming
- High strength and heat resistance gears, bearing, sealing elements, etc.
- To produce non-toxic fire retardant products

Properties	Units	Dexnyl™ 232 PI-s
Density	g/cm ³	1.36
Glass Transition Temperature \geq	°C	232
Thermal Expansion Coefficient	10 ⁻⁵ /°C	5.7
Tensile Strength \geq	MPa	110
Tensile Modulus	GPa	1.4
Elongation at Break \geq	%	27
Flexural Modulus	GPa	2.67
Compressive Strength \geq	MPa	153
Impact Strength \geq	KJ/m ²	150
Friction Coefficient	-	0.24
Dielectric Coefficient	-	3.4
Dielectric Loss	-	2.1x10 ⁻⁴
Breakdown Potential \geq	KV/mm	25
Volume Resistivity \geq	Ω .m	1.0x10 ¹⁶
Shore D-Hardness \geq	HD	85.0
Water absorption <	%	0.3

Distributed by

BIEGLO GmbH

Bahrenfelder Straße 242
22765 Hamburg
+49 40 4011 30000
info@bieglo.com
www.bieglo.com
www.polyimide-shop.de

The specified values are established from average values of several tests and they correspond to our today's knowledge. They are only to be used as information about our products and as help for the material selection. With these values, we do not ensure specific properties, or the suitability for certain application. No warranty, representation, guarantee or legally binding product description is provided by publishing this informational data.

For information about divergent properties do not hesitate to contact us. On request we advise you regarding the most appropriate component design and the definition of material specifications more suitable to your application data. Notwithstanding, the customer bears all the responsibility for the thorough examination of suitability, efficiency, efficacy and safety of the chosen products in pharmaceutical applications, medical devices or other end uses. Status: June 2019